

Technical Note

Secondary LDO Regulator Series for Local Power Supplies

ROHM Electronic Components

1A Secondary LDO Regulators for Local Power Supplies

BADDBC0 Series, BADDBC0W Series, BA00BC0W Series

No.09024EAT02

Description

The BA \square BC0 are low-saturation regulators with an output current of 1.0 A and an output voltage accuracy of ±2%. A broad output voltage range is offered, from 1.5V to 10V, and built-in overcurrent protection and thermal shutdown (TSD) circuits prevent damage due to short-circuiting and overloading, respectively.

Features

- 1) Output current: 1 A (min.)
- 2) Output voltage accuracy: ±2%
 - Broad output range available: 1.5 V -10 V (BADDBC0 series)
- 3) Low saturation-voltage type with PNP output
- 4) Built-in overcurrent protection circuit
- 5) Built-in thermal shutdown circuit
- 6) Integrated shutdown switch (BADDBC0WT, BADDBC0WT-5, or BADDBC0WFP Series, BA00BC0WCP-V5)
- 7) Operating temperature range: -40°C to +105°C

Applications

All electronic devices that use microcontrollers and logic circuits

Product Lineup

i oddot =iniodp													
Part Number	1.5	1.8	2.5	3.0	3.3	5.0	6.0	7.0	8.0	9.0	10.0	Variable	Package
BADDBC0WT	0	0	0	0	0	0	0	0	0	0	0	0	TO220FP-5
BADDBC0WT-V5	0	0	0	-	0	0	-	-	-	0	-	0	TO220FP-5 (V5)
BADDBC0WFP	0	0	0	0	0	0	0	0	0	0	0	0	TO252-5
BADDBC0T	0	0	0	0	0	0	0	0	0	0	0	-	TO220FP-3
BADDBC0FP	0	0	0	0	0	0	0	0	0	0	0	-	TO252-3
BA00BC0WCP-V5	-	-	-	-	-	-	-	-	-	-	-	0	TO220CP-V5

Part Number: BA

-			
	а	b	С

Symbol	Description								
		Output voltag	e specification						
		Output voltage (V)		Output voltage (V)					
	15	1.5 V typ	60	6.0 V typ					
	18	1.8 V typ	70	7.0 V typ					
а	25	2.5 V typ	80	8.0 V typ					
	30	3.0 V typ	90	9.0 V typ					
	33	3.3 V typ	JO	10.0 V typ					
	50	5.0 V typ	00	Variable					
b	Existence of switch	With W: A shutdown switch is prov Without W: No shutdown switch is							
С	FF	TO20FP-5, TO220FP-5(V5), TO2 P: TO252-5, TO252-3 P: TO220CP-V5	20FP-3						

●Absolute Maximum Ratings (Ta = 25°C)

P	arameter	Symbol	Limits	Unit
Power supp	ly voltage	Vcc	18 ^{*1}	V
	TO252-3		1200 ^{*2}	
	TO252-5		1300 ^{*3}	
Power	TO220FP-3	р.	2000 ^{*4}	mW
dissipation	TO220FP-5	Pd	2000 ^{*4}	
	TO220FP-5 (V5)		2000 ^{*4}	
	TO220CP-V5		2000 ^{*4}	
Operating te	mperature range	Topr	−40 to +105	°C
Ambient storage temperature		Tstg	−55 to +150	°C
Maximum ju	nction temperature	Tjmax	150	°C

*1 Must not exceed Pd.

*2 Derated at 9.6mW/°C at Ta>25°C when mounted on a glass epoxy board (70 mm × 70 mm × 1.6 mm).

*3 Derated at 10.4mW/°C at Ta>25°C when mounted on a glass epoxy board (70 mm × 70 mm × 1.6 mm).

*4 Derated at 16mW/°C at Ta> 25°C

Recommended Operating Conditions

Parameter	Symbol	Min.	Max.	Unit
Input power supply voltage	Vcc ^{*5}	3.0	16.0	V
Input power supply voltage	Vcc*6	Vo+1.0	16.0	V
Output current	lo	-	1	А
Variable output voltage setting value	Vo	1.5	12	V

*5 When output voltage is 1.5 V, 1.8 V, or 2.5 V.

*6 When output voltage is 3.0 V or higher.

•Electrical Characteristics

BADDBC0FP/T/WFP/WT (-V5)

(Unless otherwise specified, Ta = 25°C; VCTL = 3 V; VCCDC^{*7})

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Output voltage	Vo	Vo (T) ×0.98	Vo (T)	Vo (T) × 1.02	V	lo = 200mA
Shutdown circuit current	lsd	-	0	10	μA	VCTL = 0 V while in off mode
Minimum I/O voltage difference*8	ΔVd	-	0.3	0.5	V	Io = 200 mA, Vcc = $0.95 \times Vo$
Output current capacity	lo	1	-	-	Α	
Input stability ^{*9}	Reg.I	-	15	35	mV	Vcc = Vo+1.0V→16V, Io = 200mA
Load stability	Reg.L	-	35	75	mV	lo = 0 mA →1 A
Temperature coefficient of output voltage ^{*10}	Тсvо	-	±0.02	-	%/°C	lo = 5 mA, Tj = 0°C to 125°C

Vo (T): Set output voltage

*7 Vo = 1.5 V, 1.8 V, 2.5 V : Vcc = 3.3 V, Vo = 3.0 V, 3.3 V : Vcc = 5 V,

Vo = 5.0 V : Vcc : 8 V, Vo = 6.0 V : Vcc = 9 V, Vo = 8.0 V : Vcc = 11 V,

Vo = 9.0 V : Vcc = 12 V, Vo = 10.0 V : Vcc = 13 V

*8 Vo≥3.3 V

*9 Change Vcc from 3.0 V to 6 V if $1.5 V \le Vo \le 2.5 V$.

*10 Operation guaranteed

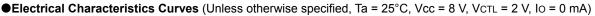
BA00BC0WFP/WT (-V5)/CP-V5

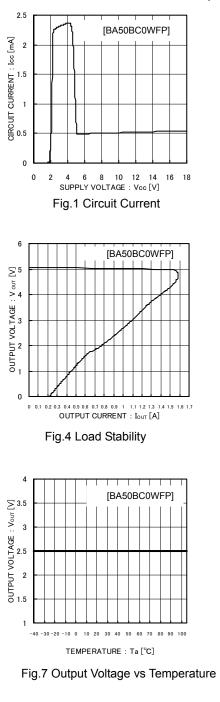
(Unless otherwise specified, Ta = 25°C, Vcc = 3.3 V, VcTL = 3 V, R1 = 30 k Ω , R2 = 30 k Ω^{*11})

Symbol	Min.	Тур.	Max.	Unit	Conditions
Isd	-	0	10	μA	VCTL = 0 V while in OFF mode
Vc	1.225	1.250	1.275	V	lo = 50 mA
ΔVd	-	0.3	0.5	V	lo = 500 mA, Vcc = 2.5V
lo	1	-	-	Α	
Reg.I	-	15	30	mV	Vcc = Vo + 1.0 V→16V, Io = 200 mA
Reg.L	-	35	75	mV	lo = 0 mA →1A
Тсvо	-	±0.02	-	%/°C	lo = 5mA, Tj=0°C to 125°C
	Isd Vc ΔVd Io Reg.I Reg.L	Isd - Vc 1.225 ΔVd - Io 1 Reg.I - Reg.L -	Isd - 0 Vc 1.225 1.250 ΔVd - 0.3 Io 1 - Reg.I - 15 Reg.L - 35	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$

*11 VOUT = Vc × (R1 + R2) / R1 (V)

*12 Operation guaranteed





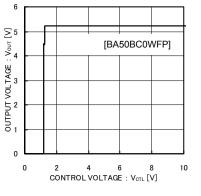
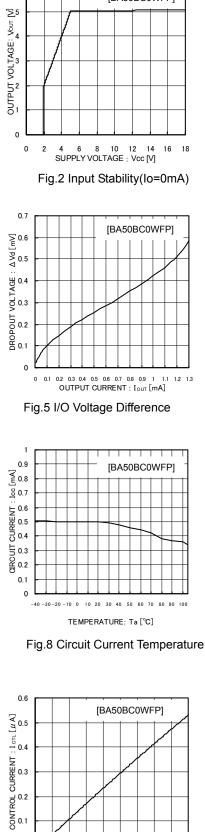
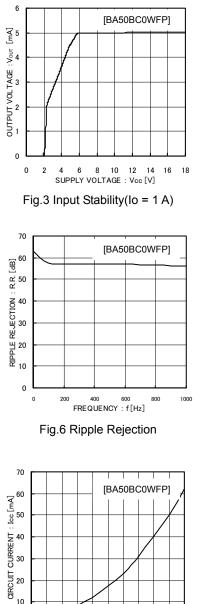


Fig.10 CTL Voltage vs Output Voltage





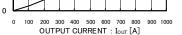


Fig.9 Circuit Current Classified by Load

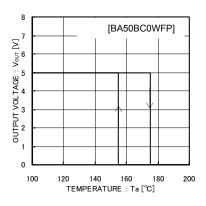


Fig.12 Thermal Shutdown Circuit

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CONTROL VOLTAGE : VCTL [V]

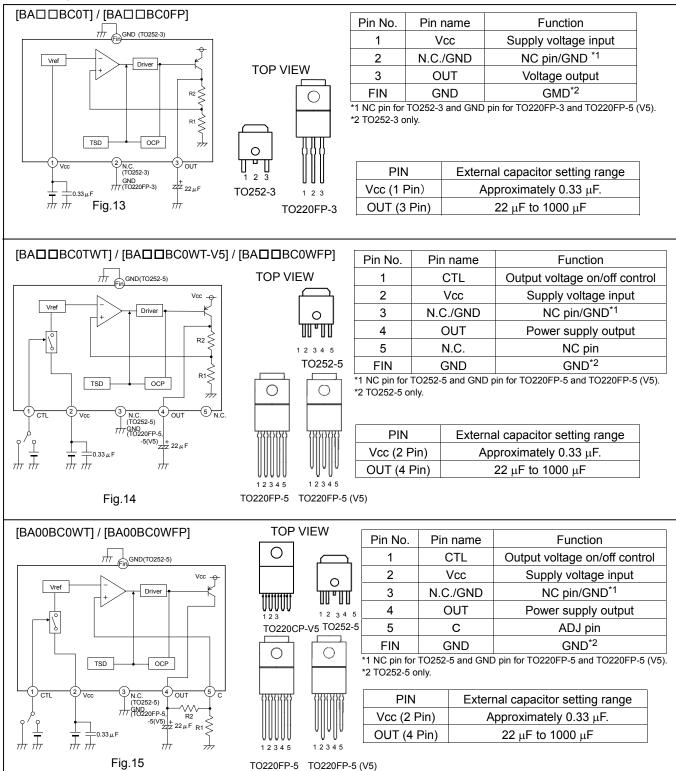
Fig.11 CTL Voltage vs CTL Current

8 10 12 14 16 18

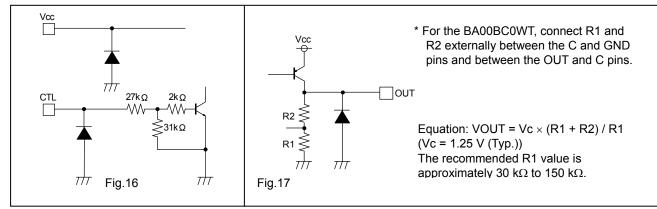
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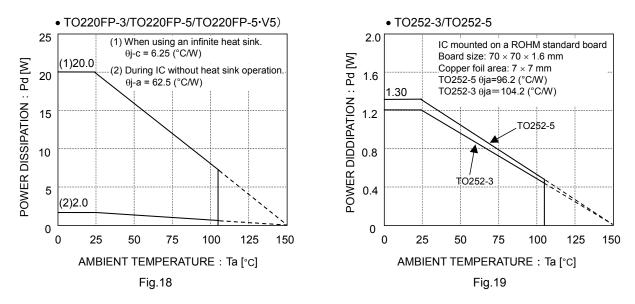
Block Diagrams / Standard Example Application Circuits



●Input / Output Equivalent Circuit Diagrams



•Thermal Derating Curves



The characteristics of the IC are greatly influenced by the operating temperature. If the temperature exceeds the maximum junction temperature T_{jmax}, deterioration or damage may occur. Implement proper thermal designs to ensure that power dissipation is within the permissible range in order to prevent instantaneous damage resulting from heat and maintain the reliability of the IC for long-term operation.

The following method is used to calculate the power consumption Pc (W).

 $Pc = (Vcc - Vo) \times Io + Vcc \times Icca$ Power dissipation $Pd \ge Pc$

The load current lo is calculated:

$$lo \leq \frac{Pd - Vcc \times lcca}{Vcc - Vo}$$

Calculation Example: Vcc = 6.0 V and Vo = 5.0 V at Ta = 85°C

 $lo \le 550 \text{ mA} (lcca \approx 20 \text{ mA})$

Refer to the above and implement proper thermal designs so that the IC will not be used under excessive power dissipation conditions under the entire operating temperature range.

 θ ja = 96.2°C/W \rightarrow -10.4 mW/°C 25°C = 1300 mW \rightarrow 85°C = 676 mW

The power consumption Pc of the IC in the event of shorting (i.e. the Vo and GND pins are shorted) can be obtained from the following equation:

 $Pc = Vcc \times (Icca + Ishort)$ (Ishort: short current).

Vcc	: Input voltage
Vo	: Output current
10	: Load current
lcca	: Circuit current

Notes for use

- Vcc pin
 - Insert a capacitor (0.33 µF approx.) between VCC and GND.

The capacitance will vary depending on the application. Use a suitable capacitance and implement designs with sufficient margins.

GND pin

Verify that there is no potential difference between the ground of the application board and the IC. If there is a potential difference, the set voltage will not be output accurately, resulting in unstable IC operation. Therefore, lower the impedance by designing the ground pattern as wide and as short as possible.

CTL pin

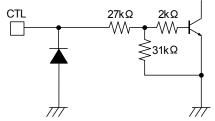
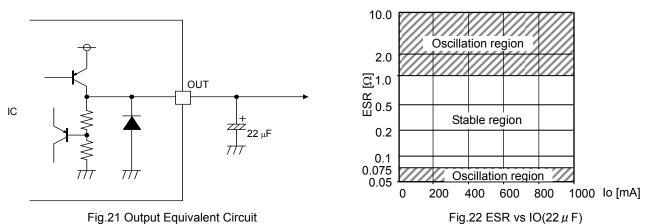


Fig.20 Input Equivalent Circuit

The CTL pin turns on at an operating power supply voltage of 2.0 V or higher and turns off at 0.8 V or lower. There is no particular order when turning the power supply and CTL pins on or off.

•Vo pin

linsert a capacitor between the Vo and GND pins in order to prevent output oscillation.



The capacitance may vary greatly with temperature changes, thus making it impossible to completely prevent oscillation. Therefore, use a tantalum aluminum electrolytic capacitor with a low ESR (Equivalent Serial Resistance). The output will oscillate if the ESR is too high or too low, so refer to the ESR characteristics in Fig. 20 and operate the IC within the stable region. Use a capacitor within a capacitance between 22μ F and $1,000\mu$ F.

Below figure, it is ESR-to-lo stability Area characteristics, measured by 22μ F -ceramic-capacitor and resistor connected in series. This characteristics is not equal value perfectly to 22μ F -aluminum electrolytic capacitor in order to measurement method. Note, however, that the stable range suggested in the figure depends on the IC and the resistance load involved, and can vary with the board's wiring impedance, input impedance, and/or load impedance. Therefore, be certain to ascertain the final status of these items for actual use.

Keep capacitor capacitance within a range of 22μ F \sim 1000 μ F. It is also recommended that a 0.33μ F bypass capacitor be connected as close to the input pin-GND as location possible. However, in situations such as rapid fluctuation of the input voltage or the load, please check the operation in real application to determine proper capacitance.

Notes for use

1. Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2. GND voltage

The potential of GND pin must be minimum potential in all operating conditions.

3. Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

4. Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

5. Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

6. Testing on application boards

When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting or storing the IC.

7. Regarding input pin of the IC

This monolithic IC contains P+ isolation and P substrate layers between adjacent elements in order to keep them isolated. P-N junctions are formed at the intersection of these P layers with the N layers of other elements, creating a parasitic diode or transistor. For example, the relation between each potential is as follows:

When GND > Pin A and GND > Pin B, the P-N junction operates as a parasitic diode.

When GND > Pin B, the P-N junction operates as a parasitic transistor.

Parasitic diodes can occur inevitable in the structure of the IC. The operation of parasitic diodes can result in mutual interference among circuits, operational faults, or physical damage. Accordingly, methods by which parasitic diodes operate, such as applying a voltage that is lower than the GND (P substrate) voltage to an input pin, should not be used.

8. Ground Wiring Pattern

When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

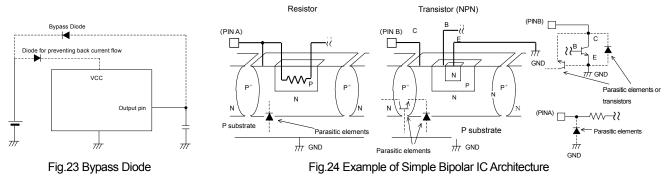
9. Thermal shutdown circuit

The IC incorporates a built-in thermal shutdown circuit (TSD circuit). The thermal shutdown circuit (TSD circuit) is designed only to shut the IC off to prevent thermal runaway. It is not designed to protect the IC or guarantee its operation. Do not continue to use the IC after operating this circuit or use the IC in an environment where the operation of this circuit is assumed.

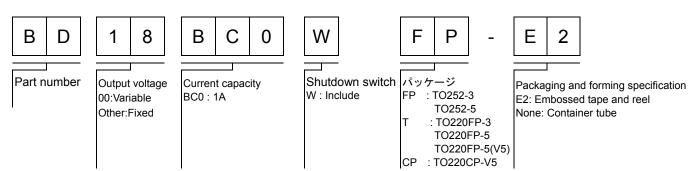
10. Overcurrent Protection Circuit

An overcurrent protection circuit is incorporated in order to prevention destruction due to short-time overload currents. Continued use of the protection circuits should be avoided. Please note that the current increases negatively impact the temperature.

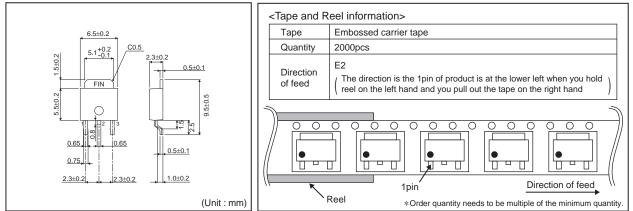
11. Damage to the internal circuit or element may occur when the polarity of the Vcc pin is opposite to that of the other pins in applications. (I.e. Vcc is shorted with the GND pin while an external capacitor is charged.) Use a maximum capacitance of 1000µF for the output pins. Inserting a diode to prevent back-current flow in series with Vcc or bypass diodes between Vcc and each pin is recommended.



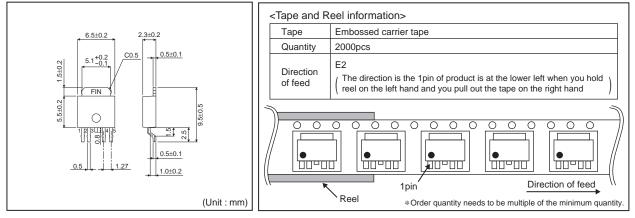
Ordering part number



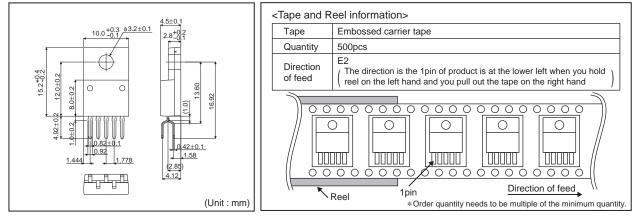
TO252-3



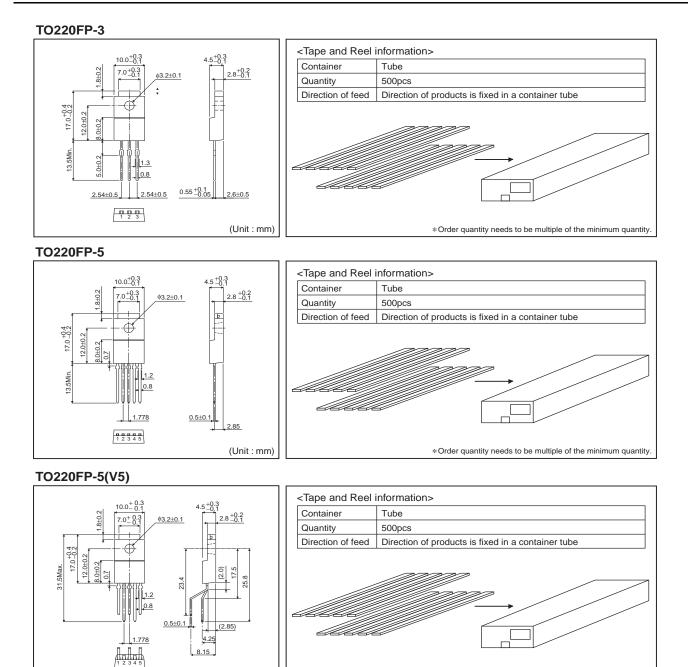
TO252-5



TO220CP-V5



(Unit : mm)



 \ast Order quantity needs to be multiple of the minimum quantity.

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